

ABSTRACT

Embodiments of the present application provides a static pressure pad, a grinding device and a silicon wafer. The static pressure pad is used for clamping, in pairs, both sides of each silicon wafer in a double-sided grinding device for the silicon wafer, the static pressure pad includes: a base having a fixed plane facing the silicon wafer; static pressure blocks uniformly distributed along a vertical direction on and extending outward from the fixing plane, and configured to provide hydrostatic pressure to the silicon wafer through fluid, to support one side of the silicon wafer in a non-contact manner; a driving module, configured to drive, when a first plane formed by an end of the static pressure block is not parallel to a target plane where the silicon wafer is positioned, each static pressure block to move in a direction perpendicular to the fixed plane, to allow the first plane to be parallel to the target plane.

(Figure 3)